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- Inputs Are TTL-Voltage Compatible
- Speed of Bipolar F, AS, and S, With Significantly Reduced Power Consumption
- Designed Specifically for High-Speed Memory Decoders and Data-Transmission Systems
- Incorporate Three Enable Inputs to Simplify Cascading and/or Data Reception
- Balanced Propagation Delays
- ±24-mA Output Drive Current
 Fanout to 15 F Devices
- SCR-Latchup-Resistant CMOS Process and Circuit Design
- Exceeds 2-kV ESD Protection Per MIL-STD-883, Method 3015

description/ordering information

The 'ACT138 decoders/demultiplexers are designed for high-performance memory-decoding and data-routing applications that require very short propagation-delay times. In high-performance memory systems, these decoders can be used to minimize the effects of system decoding. When employed with high-speed memories utilizing a fast enable circuit, the delay times of these decoders and the enable time of the memory usually are less than the typical access time of the memory. This means that the effective system delay introduced by the decoders is negligible.

The conditions at the binary-select inputs and the three enable inputs select one of eight output lines. Two active-low and one active-high enable inputs reduce the need for external gates or inverters when expanding. A 24-line decoder can be implemented without external inverters, and a 32-line decoder requires only one inverter. An enable input can be used as a data input for demultiplexing applications (see Application Information).

TA	РАСКА	GE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
	PDIP – E	Tube	CD74ACT138E	CD74ACT138E		
–55°C to 125°C	SOIC – M	Tube	CD74ACT138M	ACT138M		
-55 C 10 125 C	301C - M	Tape and reel	CD74ACT138M96	ACTISON		
	CDIP – F	Tube	CD54ACT138F3A	CD54ACT138F3A		

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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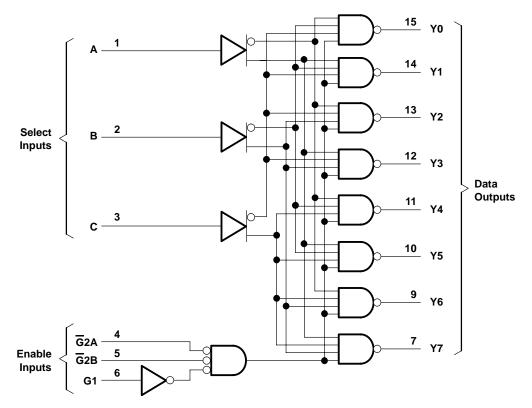
Copyright © 2003, Texas Instruments Incorporated On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

CD74ACT13	8.	B F PACKAGE E OR M PACKAGE PP VIEW)
Α [1	
в [2	15] Y0
с [3	14] Y1
G2A	4	13] Y2
G2B	5	12 Y3
G1 [6	11 🛛 Y4
Y7 [7	10 Y5
gnd [8	9] Y6

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					F	UNCTIO	N TABL	E					
ENA	ENABLE INPUTS SELECT INPUTS						OUTPUTS						
G1	G2A	G2B	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Н	Х	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	Н
X	Х	н	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	Н
L	х	х	Х	Х	Х	н	Н	Н	Н	Н	Н	Н	н
н	L	L	L	L	L	L	Н	Н	Н	Н	Н	Н	н
н	L	L	L	L	н	н	L	Н	Н	Н	Н	Н	н
н	L	L	L	Н	L	н	Н	L	Н	Н	Н	Н	н
н	L	L	L	Н	н	н	Н	Н	L	Н	Н	Н	н
н	L	L	н	L	L	н	Н	Н	Н	L	Н	Н	н
н	L	L	н	L	Н	н	Н	Н	Н	Н	L	Н	Н
н	L	L	н	Н	L	н	Н	Н	Н	н	Н	L	Н
н	L	L	Н	Н	Н	н	Н	Н	Н	Н	Н	Н	L

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC}	–0.5 V to 6 V
Input clamp current, I _{IK} (VI < 0 V or VI > V _{CC}) (see Note 1)	
Output clamp current, I _{OK} (V _O < 0 V or V _O > V _{CC}) (see Note 1)	±50 mA
Continuous output current, $I_O (V_O > 0 V \text{ or } V_O < V_{CC})$	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ_{JA} (see Note 2): E package	
M package	73°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

		T _A =	25°C	–55°C to 125°C		–40° 85°	UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	
VCC	Supply voltage	4.5	5.5	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2		2		2		V
VIL	Low-level input voltage		0.8		0.8		0.8	V
VI	Input voltage	0	VCC	0	VCC	0	VCC	V
Vo	Output voltage	0	VCC	0	VCC	0	VCC	V
ЮН	High-level output current		-24		-24		-24	mA
IOL	Low-level output current		24		24		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10		10		10	ns/V

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CON	vcc	T _A = 25°C		–55°C to 125°C		–40°C to 85°C		UNIT		
				MIN	MAX	MIN	MAX	MIN	MAX		
		I _{OH} = -50 μA	4.5 V	4.4		4.4		4.4			
M		I _{OH} = -24 mA	4.5 V	3.94		3.7		3.8		v	
VOH	VI = VIH or VIL	I _{OH} = -50 mA [†]	5.5 V			3.85				v	
		I _{OH} = -75 mA [†]	5.5 V					3.85			
		I _{OL} = 50 μA	4.5 V		0.1		0.1		0.1	ł V	
	VI = VIH or VIL	I _{OL} = 24 mA	4.5 V		0.36		0.5		0.44		
VOL		$I_{OL} = 50 \text{ mA}^{\dagger}$	5.5 V				1.65				
		$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V						1.65		
l	$V_I = V_{CC} \text{ or } GND$	-	5.5 V		±0.1		±1		±1	μA	
ICC	$V_I = V_{CC}$ or GND,	IO = 0	5.5 V		8		160		80	μA	
⊿ICC‡	V _I = V _{CC} - 2.1 V		4.5 V to 5.5 V		2.4		3		2.8	mA	
Ci					10		10		10	pF	

[†] Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50- Ω transmission-line drive capability at 85°C and 75- Ω transmission-line drive capability at 125°C.

‡Additional quiescent supply current per input pin, TTL inputs high, 1 unit load

ACT INPUT LOAD TABLE

INPUT	UNIT LOAD
A, B, or C	0.83
G2A or G2B	1
G1	0.42

Unit Load is ΔI_{CC} limit specified in electrical characteristics table (e.g., 2.4 mA at 25°C).

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

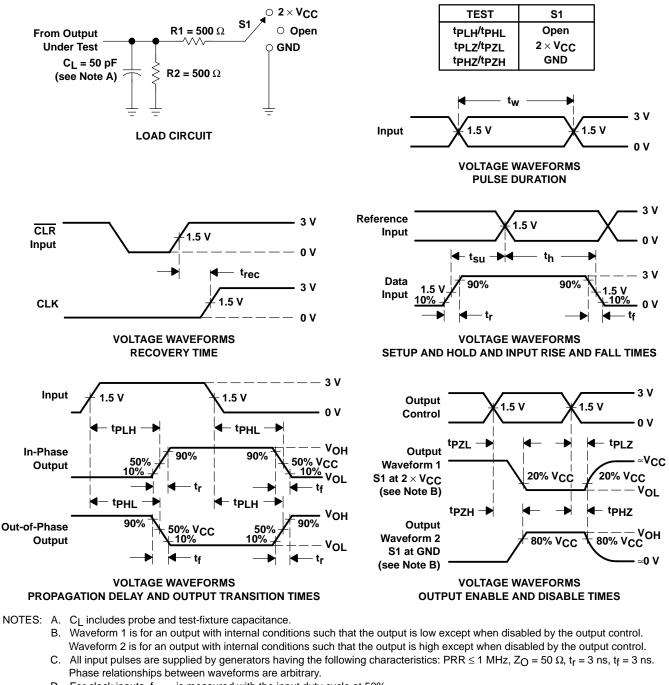
PARAMETER	FROM (INPUT)	ТО (ОИТРИТ)	–55°(125		–40°(85°	UNIT	
		(001F01)	MIN	MAX	MIN	MAX	
^t PLH	A, B, C	Any Y	3	12	3.1	10.9	ns
^t PHL	А, В, С		3	12	3.1	10.9	
^t PLH	01	Any Y	2.8	11	2.8	10	ns
^t PHL	G1		2.8	11	2.8	10	115
^t PLH	G2A, G2B		2.6	10.5	2.7	9.5	20
tPHL	GZA, GZB	Any Y	2.6	10.5	2.7	9.5	ns

operating characteristics, V_{CC} = 5 V, T_A = 25° C

	PARAMETER	TYP	UNIT
C _{pd}	Power dissipation capacitance	110	pF



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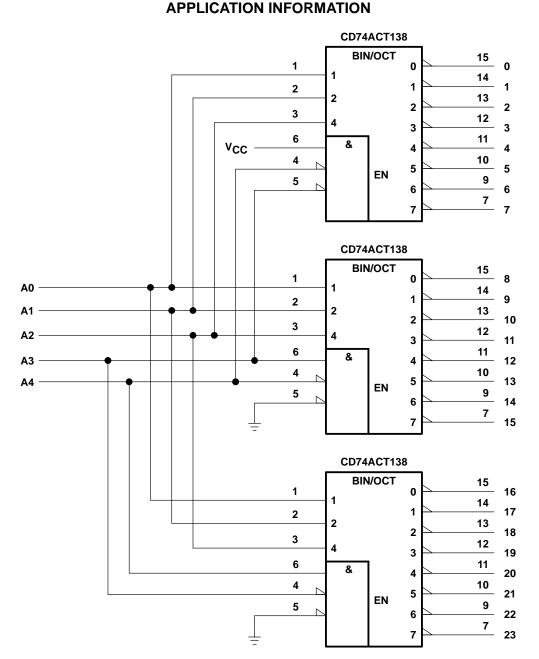
PARAMETER MEASUREMENT INFORMATION

- D. For clock inputs, f_{max} is measured with the input duty cycle at 50%.
- E. The outputs are measured one at a time with one input transition per measurement.
- F. tpLH and tpHL are the same as tpd.
- G. tp71 and tp7H are the same as ten.
- H. tpLz and tpHz are the same as tdis.
- I. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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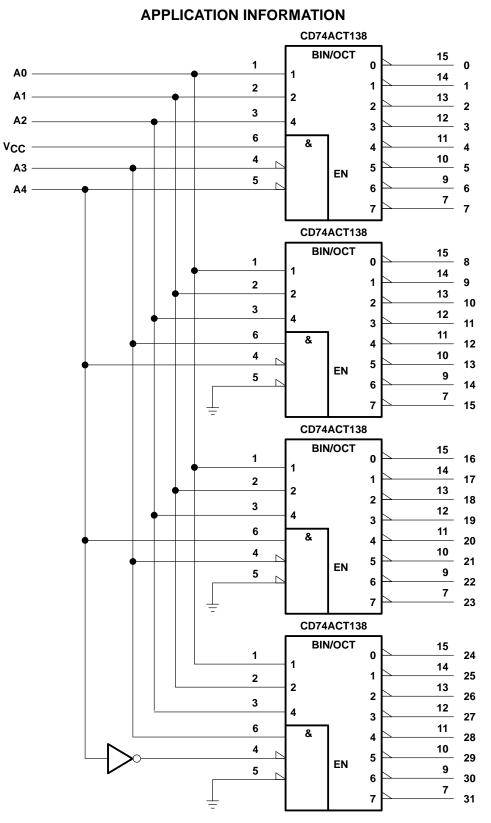


Figure 3. 32-Bit Decoding Scheme





PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
CD54ACT138F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54ACT138F3A	Samples
CD74ACT138E	ACTIVE	PDIP	Ν	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74ACT138E	Samples
CD74ACT138M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT138M	Samples
CD74ACT138M96G4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	ACT138M	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <= 1000ppm threshold. Antimony trioxide based flame retardants must also meet the <= 1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD54ACT138, CD74ACT138 :

• Catalog : CD74ACT138

Military : CD54ACT138

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications



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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



Device Deskare Des
*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74ACT138M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



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PACKAGE MATERIALS INFORMATION

12-May-2023



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74ACT138M96	SOIC	D	16	2500	340.5	336.1	32.0

TEXAS INSTRUMENTS

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12-May-2023

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CD74ACT138E	N	PDIP	16	25	506	13.97	11230	4.32
CD74ACT138E	N	PDIP	16	25	506	13.97	11230	4.32

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



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D (R-PDSO-G16) PLASTIC SMALL OUTLINE Stencil Openings (Note D) Example Board Layout (Note C) –16x0,55 -14x1,27 -14x1,27 16x1,50 5,40 5.40 Example Non Soldermask Defined Pad Example Pad Geometry (See Note C) 0,60 .55 Example 1. Solder Mask Opening (See Note E) -0,07 All Around

NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



J (R-GDIP-T**) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



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